



GROUP 1700

APR 18 2003

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PATENT  
0599-0207P

IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant: Yasushi SAWAMURA et al. Conf.: 7250  
Appl. No.: 09/940,513 / Group: <sup>1719</sup>1771 /  
Filed: August 29, 2001 Examiner: <sup>Keehan</sup>~~V. CHANG~~

For: ADHESIVE SHEET FOR SEMICONDUCTOR  
CONNECTING SUBSTRATE, ADHESIVE-BACKED  
TAPE FOR TAB, ADHESIVE-BACKED TAPE FOR  
WIRE BONDING CONNECTION, SEMICONDUCTOR  
CONNECTING SUBSTRATE, AND SEMICONDUCTOR  
DEVICE

LETTER SUBMITTING FORMAL DRAWINGS

Assistant Commissioner for Patents  
Washington, DC 20231

April 15, 2003

Sir:

Attached hereto is/are thirteen (13) sheet(s) of formal drawings which comply with the provisions of 37 C.F.R. § 1.84. The drawings should be made a part of the record of the above-identified application.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies, to charge payment or credit any overpayment to Deposit Account No. 02-2448 for any additional fees required under 37 C.F.R. §§1.16 or 1.17; particularly, extension of time fees.

Respectfully submitted,

BIRCH, STEWART, KOLASCH & BIRCH, LLP

By 

Andrew D. Meikle, #32,868

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Attachments